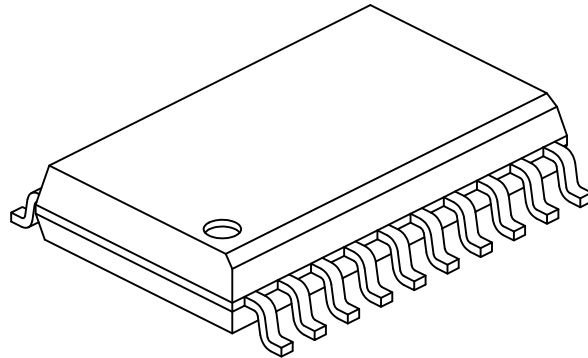
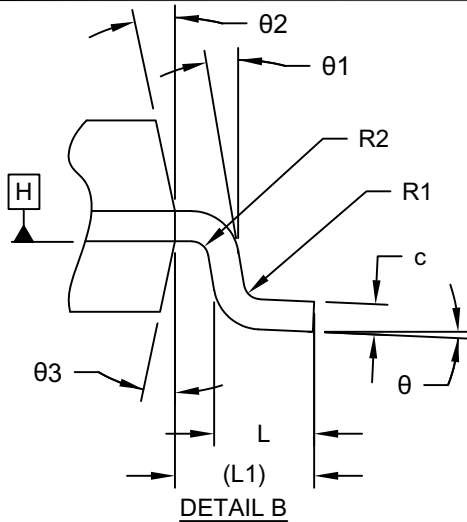


20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



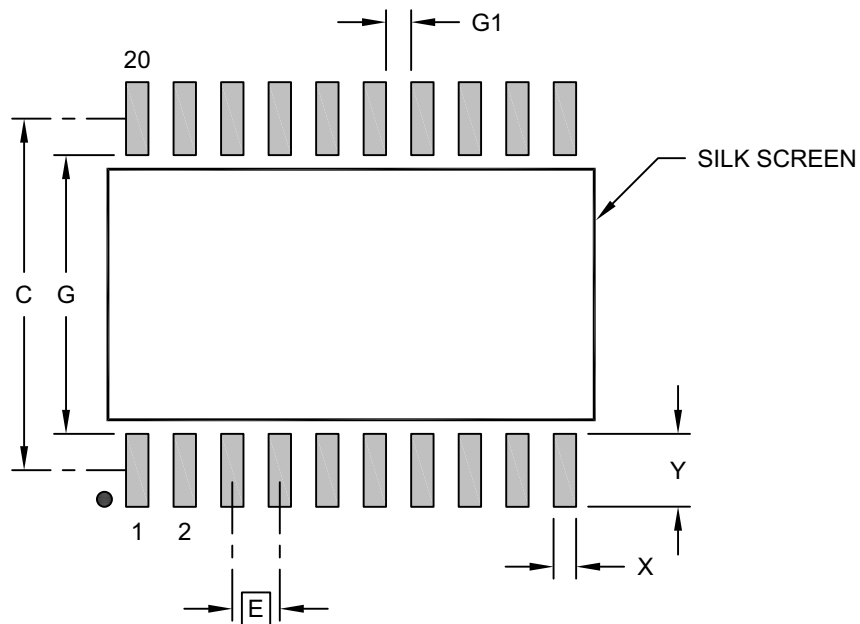
Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Number of Terminals	N	20		
Pitch	e	1.27 BSC		
Overall Height	A	-	-	2.65
Standoff §	A1	0.10	-	0.30
Molded Package Thickness	A2	2.05	-	-
Overall Length	D	12.78 BSC		
Overall Width	E	10.33 BSC		
Molded Package Width	E1	7.49 BSC		
Terminal Width	b	0.31	-	0.51
Terminal Thickness	c	0.25	-	0.75
Corner Chamfer	h	0.25	-	0.75
Terminal Length	L	0.40	0.65	1.27
Footprint	L1	1.40 REF		
Lead Bend Radius	R1	0.07	-	-
Lead Bend Radius	R2	0.07	-	-
Foot Angle	θ	0°	-	8°
Lead Angle	θ1	0°	-	-
Mold Draft Angle	θ2	5°	-	15°
Mold Draft Angle	θ3	5°	-	15°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.
- Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- § Significant Characteristic

20-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Contact Pad Spacing	C		9.40	
Contact Pad Width (X20)	X			0.60
Contact Pad Length (X20)	Y			1.95
Contact Pad to Contact Pad	G	0.67		
Contact Pad to Contact Pad	G1	7.45		

Notes:

- Dimensioning and tolerancing per ASME Y14.5M
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process